

SIMATIC IPC547G (Rack PC, 19", 4HU); Interfaces: 2x USB 3.0 on the front; 2x Intel Gigabit Ethernet, 2x PS/2, Audio on the rear side; 7 slots: 5x PCI Express, 2x PCI, Temperature and Fan monitoring; Watchdog; Card retainer Core i7-6700 (4C/8T, 3.4 (4.0) GHz, 8 MB cache); Mainboard: (chipset H110, 1x DVI-D, 1x display port V1.2, 2x USB 3.0 and 4x USB 2.0 on the rear side) 1x 240 GB SSD, internal 8 GB DDR4 SD-RAM (2x 4 GB), Dual Channel Enclosure blue chromated, 100/240V AC industrial power supply unit, DVD +/-RW (slim) Graphics onboard Without operating system without expansions (software) Power supply cable China

Installation type/mounting	
Mounting	For horizontal and vertical installation; prepared for telescopic rails; 19" mounting bracket can be removed externally; tower kit (optional)
Design	Rack PC, 19", 4U
Supply voltage	
Type of supply voltage	100/240 V AC (autorange) 50 / 60 Hz; optional redundant 100/240 V AC
Line frequency	
• Rated value 50 Hz	Yes
• Rated value 60 Hz	Yes
Mains buffering	
• Mains/voltage failure stored energy time	20 ms
Processor	
Processor type	Xeon E3-1275 v5 (4C/8T, 3.6 (4.0) GHz, 8 MB Cache); Core i7-6700 (4C/8T, 3.4 (4.0) GHz, 8 MB Cache); Core i5-6500 (4C/4T, 3.2 (3.6) GHz, 6 MB Cache); Pentium G4400 (2C/2T, 3.3 GHz, 3 MB Cache)
Chipset	Intel C236 / Intel H110
Graphic	
Graphics controller	Onboard Intel HD graphics P530 / 530 / 510 integrated in processor; graphics card PCIe (x16) (dual head: 2x VGA or 2x DVI-D) (optional)
Drives	
Optical drives	DVD±R/RW (SlimLine)
Hard disk	Internal installation: 1 TB HDD, 2x 1 TB HDD, RAID1 (2x 1 TB HDD), RAID1 (2x 1 TB HDD (Enterprise)); for front mounting in low-profile removable drive bay trays (hot-swap in RAID configuration): 1 TB HDD, 2x 1 TB HDD, RAID1 (2x 1 TB HDD), RAID1 (2x 1 TB HDD (Enterprise)), RAID1 (2x 2 TB HDD (Enterprise)), RAID1 (2x 2 TB HDD (Enterprise)) + 1x 2 TB HDD (Enterprise) as hot spare, RAID1 (2x 2 TB HDD (Enterprise)) + 1x 480 GB SSD, RAID5 (3x 2 TB HDD (Enterprise)), RAID5 (3x 2 TB HDD (Enterprise)) + 1x 2 TB HDD (Enterprise) as hot spare
SSD	Yes; 1x 240 GB, 1x 480 GB SSD, 2x 480 GB SSD, RAID1 (2x 480 GB SSD)
Slot for drives	Mounted internally in vibration/shock-absorbing hard disk support, or mounted at the front in the low-profile removable drive bay (hot-swap in RAID configurations)
Memory	
Main memory	4 GB to 64 GB DDR4-2133 SDRAM
Capacity of main memory, max.	64 Gbyte
Hardware configuration	
Slots	
• free slots	7 spare slots for expansions (all long); mainboard with H110 chipset: 1x PCIe (x16) Gen 3, 1x PCIe (x16) (1 lane) Gen 2, 1x PCIe (x8) (1 lane) Gen 2, 1x PCIe (x4) (1 lane) Gen 2, 1x PCIe (x4) (1 lane) Gen 2, 2x PCI; mainboard with C236 chipset: 1x PCIe (x16) Gen 3, 1x PCIe (x16) (4 lanes) Gen 3, 1x PCIe (x8) (1 lane) Gen 3, 1x PCIe (x4) (4 lane) Gen 3, 1x PCIe (x4) (1 lane) Gen 3, 2x PCI
Interfaces	
Interfaces/bus type	Interfaces mainboard (H110 chipset): 2x Intel Gigabit Ethernet (RJ45, teaming-capable), 4x USB 3.0: 2x on rear, 2x on front, 4x USB 2.0: 4x

	on rear, 1x DisplayPort V1.2, 1x DVI-D, 2x PS/2, audio: Line in, line out, micro; interfaces mainboard (C236 chip set): 2x Intel Gigabit Ethernet (RJ45, teaming-capable), 6x USB 3.0: 4x on rear, 2x on front, 5x USB 2.0: 4x on rear, 1x internal e.g. for software dongle with optional interlock, 2x DisplayPort V1.2, 1x DVI-D, 1x COM1, 2x PS/2, audio: line in, line out, micro
USB port	Mainboard (H110 chipset): 4x USB 3.0: 2x on rear, 2x on front, 4x USB 2.0: 4x on rear; mainboard (C236 chipset): 6x USB 3.0: 4x on rear, 2x on front, 5x USB 2.0: 4x on rear, 1x internal e.g. for software dongle with optional interlock
Connection for keyboard/mouse	2x PS/2
serial interface	COM1: 1x RS 232, COM2 (optional): 1x RS 232
parallel interface	optional LPT1
Multimedia	
• Audio In/Out	Yes
• Microphone In	Yes
Video interfaces	
• Graphics interface	2x DisplayPort and 1x DVI-D onboard; 1x VGA via DP-VGA adapter cable (optional); graphics card PCIe (x16), Dual Head (2x VGA or 2x DVI-D), 1 GB graphics memory (optional)
Industrial Ethernet	
• Industrial Ethernet interface	2x Ethernet (RJ45)
— 100 Mbps	Yes
— 1000 Mbps	Yes
Integrated Functions	
Monitoring functions	
• Temperature monitoring	Yes
• Watchdog	Yes
• Status LEDs	POWER, HDD, TEMP, FAN, HDD0 ALARM, HDD1 ALARM, HDD2 ALARM, HDD3 ALARM
• Fan	Yes
• Monitoring function via network	Optional
EMC	
Interference immunity against discharge of static electricity	
• Interference immunity against discharge of static electricity	±4 kV contact discharge acc. to IEC 61000-4-2; ±8 kV air discharge acc. to IEC 61000-4-2
Interference immunity against high-frequency electromagnetic fields	
• Interference immunity against high frequency radiation	10 V/m for 80 - 1 000 MHz, 80% AM acc. to IEC 61000-4-3; 3 V/m for 1.4 - 2 GHz, 80% AM acc. to IEC 61000-4-3; 1 V/m for 2 - 2.7 GHz, 80% AM acc. to IEC 61000-4-3; 10 V for 150 kHz - 80 MHz, 80% AM acc. to IEC 61000-4-6
Interference immunity to cable-borne interference	
• Interference immunity on supply cables	±2 kV acc. to IEC 61000-4-4, burst; ±1 kV acc. to IEC 61000-4-5, surge symmetric; ±2 kV acc. to IEC 61000-4-5, surge asymmetric
• Interference immunity on signal cables >30m	±2 kV acc. to IEC 61000-4-4, burst; ±2 kV acc. to IEC 61000-4-5, surge
• Interference immunity on signal cables < 30m	±1 kV acc. to IEC 61000-4-4, Burst
Interference immunity against voltage surge	
• asymmetric interference	±2 kV acc. to IEC 61000-4-5, surge asymmetric
• symmetric interference	±1 kV acc. to IEC 61000-4-5, surge symmetric
Interference immunity to magnetic fields	
• Interference immunity to magnetic fields at 50 Hz	30 A/m; to IEC 61000-4-8
Emission of conducted and non-conducted interference	
• Interference emission via line/AC current cables	EN 61000-6-3, FCC Class A, EN 61000-6-4, CISPR 22, EN 55022 Class B, EN 61000-3-2 Class D, EN 61000-3-3
Degree and class of protection	
IP (at the front)	IP30
IP (rear)	IP20
Standards, approvals, certificates	
CE mark	Yes; For use in industrial areas as well as domestic, business and commercial environments (emitted interference: EN 61000-6-3:2007 +A1:2011, noise immunity: EN 61000-6-2:2005)
CSA approval	Yes; CAN/CSA-C22.2 No. 61010-2-201 Second Edition
UL approval	Yes; UL 61010-2-201 Second Edition, File E85972
cULus	Yes; UL 61010-2-201 Second Edition; CAN/CSA-C22.2 No. 61010-2-

	201 Second Edition
RCM (formerly C-TICK)	Yes
KC approval	Yes
EAC (formerly Gost-R)	Yes
EMC	EN 61000-6-3; EN 61000-6-4; CISPR 22, EN 55022 Class B; FCC Class A; EN 61000-3-2 Class D; EN 61000-3-3
Dust protection	With front door closed: G2 EN 779, 99% of particles > 0.5 mm are filtered
Ambient conditions	
Ambient temperature during operation	
• Ambient temperature during operation	0 °C to +40 °C in full configuration (no burner mode), at +5 °C to +35 °C without limitation
Ambient temperature during storage/transportation	
• min.	-20 °C
• max.	60 °C
Relative humidity	
• Relative humidity	Tested according to IEC 60068-2-78, IEC 60068-2-30: Operation: 5 % to 85 % at 30 °C (no condensation), storage / transport: 5 % to 95 % at 25 / 55 °C (no condensation)
Vibrations	
• Vibration resistance during operation acc. to IEC 60068-2-6	Tested according to IEC 60068-2-6, 10 cycles; 20 to 58 Hz: 0.015 mm; 58 to 200 Hz: 2 m/s ² (0.2 g)
Shock testing	
• Shock load during operation	Tested according to IEC 60068-2-27; half-sine: 9.8 m/s ² (1 g), 20 ms, 100 shocks per axis
Operating systems	
pre-installed operating system	Windows 7 Ultimate multi-language (32-bit / 64-bit); Windows 10 Enterprise 2015 LTSC, multi-language (64-bit); Windows 10 Enterprise 2016 LTSC, multi-language (64-bit); Windows 10 IoT Enterprise 2019 LTSC, multi-language (64-bit); Windows Server 2008 R2 Standard Edition incl. 5 multi-language clients (64-bit); Windows Server 2012 R2 Standard Edition incl. 5 multi-language clients (64-bit); Windows Server 2016 Standard Edition incl. 5 multi-language clients (64-bit)
Additional info on operating system	Multi-Language User Interface (MUI): 5 languages (English, German, French, Spanish, Italian)
without operating system	Yes
Software	
SIMATIC Software	Optional package with SIMATIC WinCC
Dimensions	
Width	430 mm
Height	177 mm; 4U
Depth	446 mm; Device with short enclosure: 356 mm
last modified:	2/21/2022 